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FACSIMILE COVER SHEET

To:	Examiner Con P. Tran	From:	Robert L. Pilaud, Reg. No. 53,470
Facsimile Number:	571-273-7532	Telephone No.	571-272-7532
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In re Patent Application of:
Kazuhiko MIYATA et al.
Serial No.: 10/821,848
Filed: April 12, 2004
For: AN AUDIO SIGNAL PROCESSING CIRCUIT AND A DISPLAY DEVICE INCORPORATING THE SAME
Docket No.: 0756-7278

Dear Mr. Tran,

Further to our conversations of March 10 and 15, 2010, we approve of the further amendments to claims 22, 29 and 62. Attached for your review is a marked-up version of the claims including the agreed-upon amendments. We believe that an agreement has been reached that the attached amendments place the application in condition for allowance, and that you will issue a Notice of Allowance including an Examiner's Amendment that will effectuate entry of these amendments. Please let us know if you have any questions or concerns.

Sincerely,

Rob Pilaud
Reg. No. 53,470

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PROPOSED AMENDMENT

1.-7. (Canceled)

8. (Currently Amended) An audio signal processing circuit comprising:

an operational amplifier formed over an insulating substrate and comprising a thin film element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor;

a first chip capacitor mounted over a flexible printed circuit connected to the insulating substrate, the first chip capacitor being electrically connected to a second terminal of the second thin film resistor, and

a smoothing circuit and the smoothing circuit comprises a third thin film resistor and a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

9.-11. (Canceled)

12. (Previously Presented) The audio signal processing circuit according to claim 8, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

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13. (Previously Presented) The audio signal processing circuit according to claim 8, wherein the first thin film resistor and the second thin film resistor have a resistance value of 80 kΩ or more.

14. (Original) An electronic equipment comprising the audio signal processing circuit according to claim 8, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.

15.-21. (Canceled)

22. (Currently Amended) A display device comprising:

a pixel portion formed over an insulating substrate; and

an audio signal processing circuit, wherein the audio signal processing circuit comprises:

an operational amplifier formed over the insulating substrate and comprising a thin film element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor;

a first chip capacitor mounted around the pixel portion and over the insulating substrate, the first chip capacitor being electrically connected to a second terminal of the second thin film resistor, and

a smoothing circuit and the smoothing circuit comprises a third thin film resistor and a second chip capacitor,

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wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

23.-25. (Canceled)

26. (Previously Presented) The display device according to claim 22, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

27. (Previously Presented) The display device according to claim 22, wherein the first thin film resistor and the second thin film resistor have a resistance value of 80 kΩ or more.

28. (Original) An electronic equipment comprising the display device according to claim 22, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.

29. (Currently Amended) A display device comprising:

a pixel portion formed over an insulating substrate; and

an audio signal processing circuit, wherein the audio signal processing circuit comprises:

an operational amplifier formed over the insulating substrate and comprising a thin film element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

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a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor;

a first chip capacitor mounted over a flexible printed circuit connected to the insulating substrate, the first chip capacitor being electrically connected to a second terminal of the second thin film resistor, and

a smoothing circuit and the smoothing circuit comprises a third thin film resistor and a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

30.-32. (Canceled)

33. (Previously Presented) The display device according to claim 29, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

34. (Previously Presented) The display device according to claim 29, wherein the first thin film resistor and the second thin film resistor have a resistance value of 80 kΩ or more.

35. (Original) An electronic equipment comprising the display device according to claim 29, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.

36.-42. (Canceled)

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43. (Currently Amended) The audio signal processing circuit according to claim 8, wherein the audio signal processing circuit comprises an input circuit and the input circuit comprises the second thin film resistor and the first chip capacitor.

44. (Currently Amended) The display device according to claim 22, wherein the display device comprises an input circuit and the input circuit comprises the second thin film resistor and the first chip capacitor.

45. (Currently Amended) The display device according to claim 29, wherein the display device comprises an input circuit and the input circuit comprises the second thin film resistor and the first chip capacitor.

46. (Currently Amended) An audio signal processing circuit comprising:

an operational amplifier formed over an insulating substrate and comprising a thin film element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor;

a first chip capacitor mounted over the insulating substrate, the first chip capacitor being electrically connected to a second terminal of the second thin film resistor, and

a smoothing circuit and the smoothing circuit comprises a third thin film resistor and a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

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wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

47. (Canceled)

48. (Currently Amended) The audio signal processing circuit according to claim 46, wherein the audio signal processing circuit comprises an input circuit and the input circuit comprises the second thin film resistor and the first chip capacitor.

49.-50. (Canceled)

51. (Previously Presented) The audio signal processing circuit according to claim 46, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

52. (Previously Presented) The audio signal processing circuit according to claim 46, wherein the first thin film resistor and the second thin film resistor have a resistance value of 80 kΩ or more.

53. (Previously Presented) An electronic equipment comprising the audio signal processing circuit according to claim 46, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.

54. (Currently Amended) An audio signal processing circuit comprising:

an operational amplifier formed over an insulating substrate and comprising a thin film element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational

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amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor;

a first chip capacitor mounted over a printed circuit board electrically connected to the insulating substrate, the first chip capacitor being electrically connected to a second terminal of the second thin film resistor, and

a smoothing circuit and the smoothing circuit comprises a third thin film resistor and a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

55. (Canceled)

56. (Currently Amended) The audio signal processing circuit according to claim 54, wherein the audio signal processing circuit comprises an input circuit and the input circuit comprises the second thin film resistor and the first chip capacitor.

57.-58. (Canceled)

59. (Previously Presented) The audio signal processing circuit according to claim 54, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

60. (Previously Presented) The audio signal processing circuit according to claim 54, wherein the first thin film resistor and the second thin film resistor have a resistance value of 80 kΩ or more.

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61. (Previously Presented) An electronic equipment comprising the audio signal processing circuit according to claim 54, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.

62. (Currently Amended) A display device comprising:

a pixel portion formed over an insulating substrate; and

an audio signal processing circuit, wherein the audio signal processing circuit comprises:

an operational amplifier formed over the insulating substrate and comprising a thin film element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor;

a first chip capacitor mounted over a printed circuit board electrically connected to the insulating substrate, the first chip capacitor being electrically connected to a second terminal of the second thin film resistor, and

a smoothing circuit and the smoothing circuit comprises a third thin film resistor and a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

63. (Canceled)

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64. (Currently Amended) The display device according to claim 62, wherein the display device comprises an input circuit and the input circuit comprises the second thin film resistor and the first chip capacitor.

65.-66. (Canceled)

67. (Previously Presented) The display device according to claim 62, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

68. (Previously Presented) The display device according to claim 62, wherein the first thin film resistor and the second thin film resistor have a resistance value of 80 kΩ or more.

69. (Previously Presented) An electronic equipment comprising the display device according to claim 62, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.